

**Amendments to the Claims:**

This listing of claims replaces all prior versions, and listings, of claims in the application:

**Listing of the claims:**

Claims 1-10 (canceled)

11. (Original) A method of producing a sensor, the method comprising:  
forming a plurality of working portions on a first wafer;  
forming a plurality of through-holes and cavities on a second wafer;  
securing the second wafer to the first wafer, at least one of the cavities aligning to at least one of the working portions;  
filling the through holes with conductive material to form a plurality of conductive paths; and  
dicing the first and second wafers.
12. (Original) The method as defined by claim 11 wherein the conductive material includes electroless nickel.
13. (Original) The method as defined by claim 11 wherein securing the second wafer to the first wafer includes using a screen print seal glass.
14. (Original) The method as defined by claim 11 wherein forming a plurality of working portions on a first wafer includes forming one of accelerometer structure and gyroscope structure on the first wafer.
15. (Original) The method as defined by claim 11 wherein the conductive material in at least one of the through holes contacts at least one of the working portions.

16. (Original) The method as defined by claim 11 wherein forming a plurality of working portions includes forming MEMS structure and corresponding circuitry.

Claims 17-20 (Canceled)